

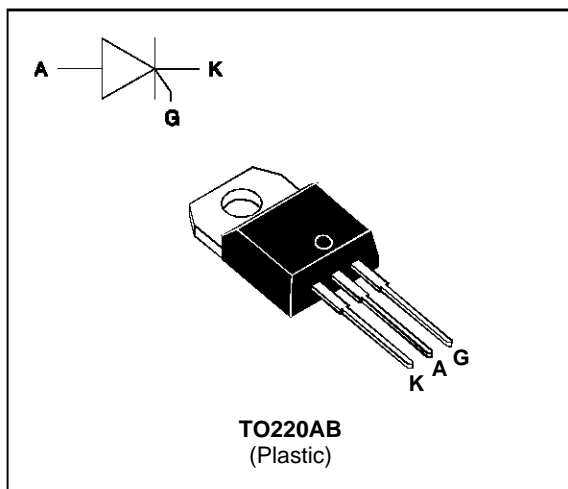
SCR FOR OVERVOLTAGE PROTECTION

FEATURES

- HIGH SURGE CURRENT CAPABILITY
- HIGH di/dt RATING
- HIGH STABILITY AND RELIABILITY

DESCRIPTION

The TYP 212 ---> 1012 Family uses high performance glass passivated chips technology. These Silicon Controlled Rectifiers are designed for overvoltage protection in crowbar circuits application.



ABSOLUTE RATINGS (limiting values)

| Symbol | Parameter | Value | Unit | |
|--------------------|---|--------------------------------|------------------|------------------|
| $I_{T(RMS)}$ | RMS on-state current (180° conduction angle, single phase circuit) | $T_c = 110\text{ °C}$ 12 | A | |
| $I_{T(AV)}$ | Average on-state current (180° conduction angle, single phase circuit) | $T_c = 110\text{ °C}$ 8 | A | |
| I_{TSM} | Non repetitive surge peak on-state current (T_j initial = 25°C) | $t_p = 8.3\text{ ms}$ | 315 | A |
| | | $t_p = 10\text{ ms}$ | 300 | |
| I^2t | I^2t value | $t_p = 10\text{ ms}$ | 450 | A ² s |
| I_{TM} | Non repetitive surge peak on-state current (T_j initial = 25°C) Exponential pulse wave form | $t_p = 1\text{ ms}$ | 750 | A |
| di/dt | Critical rate of rise of on-state current Gate supply : $I_G = 100\text{ mA}$ $di_G/dt = 1\text{ A}/\mu\text{s}$ | 100 | A/ μs | |
| T_{stg} T_j | Storage and operating junction temperature range | - 40 to + 150 - 40 to + 125 | °C °C | |
| T_l | Maximum lead temperature for soldering during 10 s at 4.5 mm from case | 260 | °C | |

| Symbol | Parameter | TYP | | | | Unit |
|------------------------|--|-----|-----|------|------|------|
| | | 212 | 512 | 1012 | 2012 | |
| V_{DRM} V_{RRM} | Repetitive peak off-state voltage $T_j = 125\text{ °C}$ | 25 | 50 | 100 | 200 | V |

THERMAL RESISTANCES

| Symbol | Parameter | Value | Unit |
|--------------|-------------------------|-------|------|
| Rth (j-a) | Junction to ambient | 60 | °C/W |
| Rth (j-c) DC | Junction to case for DC | 1.3 | °C/W |

GATE CHARACTERISTICS (maximum values)

P_G (AV) = 1W P_{GM} = 10W (tp = 20 μs) I_{FGM} = 4A (tp = 20 μs) V_{RGM} = 5 V.

ELECTRICAL CHARACTERISTICS

| Symbol | Test Conditions | Value | Unit |
|------------------------|--|-------------------|------|
| I_{GT} | $V_D=12V$ (DC) $R_L=33\Omega$ $T_j=25^\circ C$ MAX | 30 | mA |
| V_{GT} | $V_D=12V$ (DC) $R_L=33\Omega$ $T_j=25^\circ C$ MAX | 1.5 | V |
| V_{GD} | $V_D=V_{DRM}$ $R_L=3.3k\Omega$ $T_j=125^\circ C$ MIN | 0.2 | V |
| tgt | $V_D=V_{DRM}$ $I_G = 200mA$ $di_G/dt = 1.5A/\mu s$ $T_j=25^\circ C$ TYP | 1 | μs |
| I_L | $I_G = 1.2 I_{GT}$ $T_j=25^\circ C$ TYP | 60 | mA |
| I_H | $I_T = 500mA$ gate open $T_j=25^\circ C$ MAX | 50 | mA |
| V_{TM} | $I_{TM} = 50A$ tp= 380μs $T_j=25^\circ C$ MAX | 1.5 | V |
| I_{DRM} I_{RRM} | V_{DRM} Rated V_{RRM} Rated $T_j=25^\circ C$ MAX | 0.01 | mA |
| | | $T_j=125^\circ C$ | 2 |
| dV/dt | Linear slope up to $V_D=67\%V_{DRM}$ gate open $T_j=125^\circ C$ MIN | 200 | V/μs |
| tq | $V_D=67\%V_{DRM}$ $I_{TM} = 50A$ $V_R = 25V$ $di_{TM}/dt=30 A/\mu s$ $dV_D/dt= 50V/\mu s$ $T_j=125^\circ C$ TYP | 100 | μs |

Fig.1 : Maximum average power dissipation versus average on-state current.

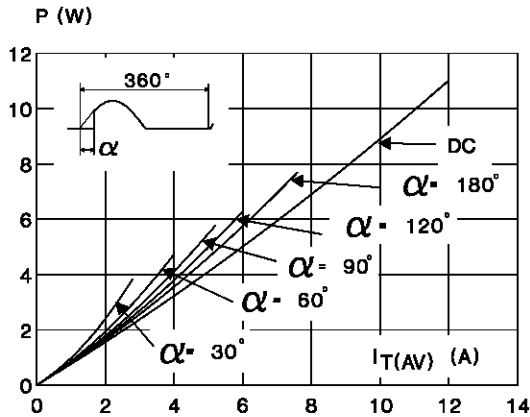


Fig.2 : Correlation between maximum average power dissipation and maximum allowable temperatures (T_{amb} and T_{case}) for different thermal resistances heatsink + contact.

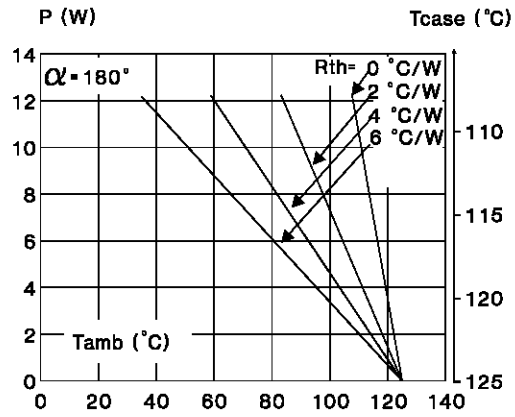


Fig.3 : Average on-state current versus case temperature.

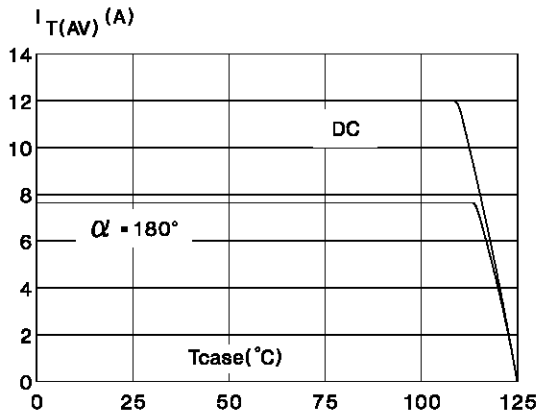


Fig.4 : Relative variation of thermal impedance versus pulse duration.

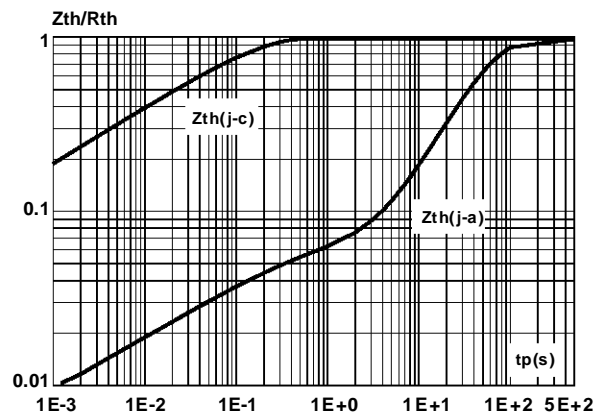


Fig.5 : Relative variation of gate trigger current versus junction temperature.

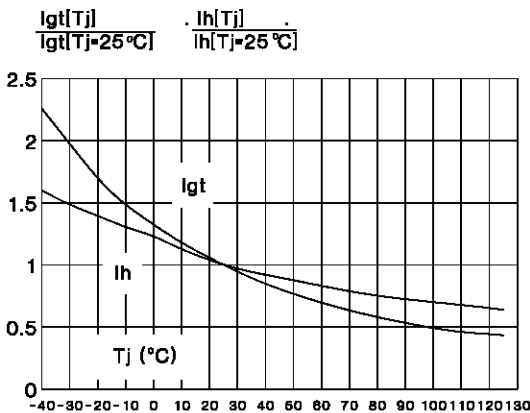
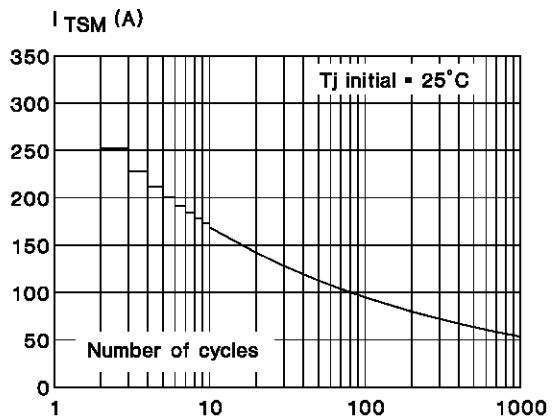


Fig.6 : Non repetitive surge peak on-state current versus number of cycles.



TYP 212 ---> TYP 2012

Fig.7 : Non repetitive surge peak on-state current for a sinusoidal pulse with width : $t \leq 10$ ms, and corresponding value of I^2t .

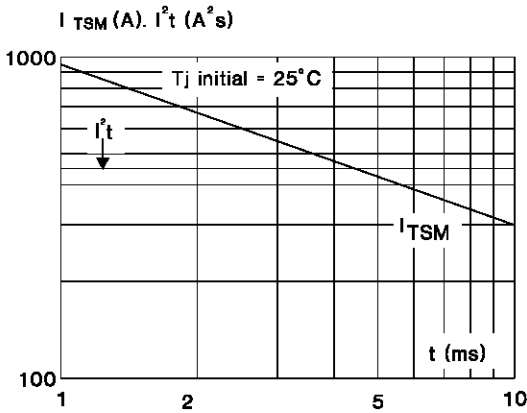


Fig.8 : On-state characteristics (maximum values).

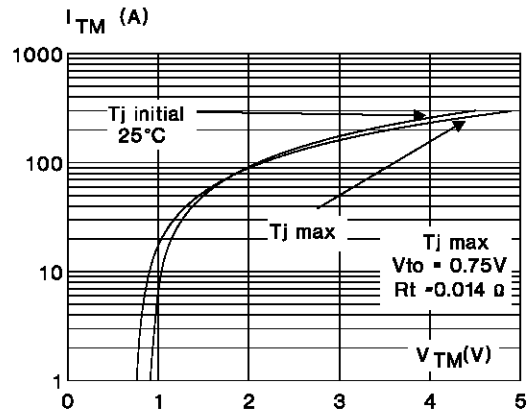


Fig.9 : Peak capacitor discharge current versus pulse width.

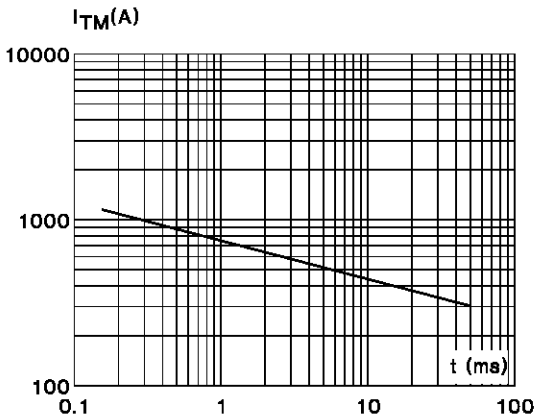
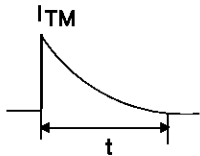
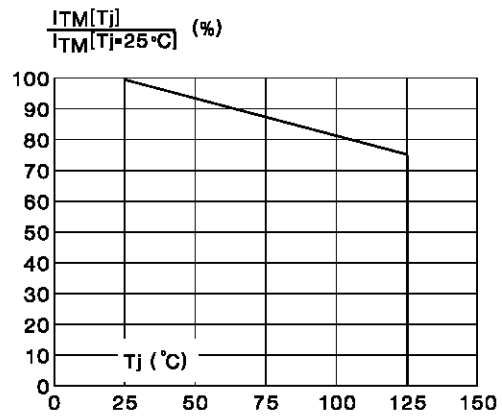
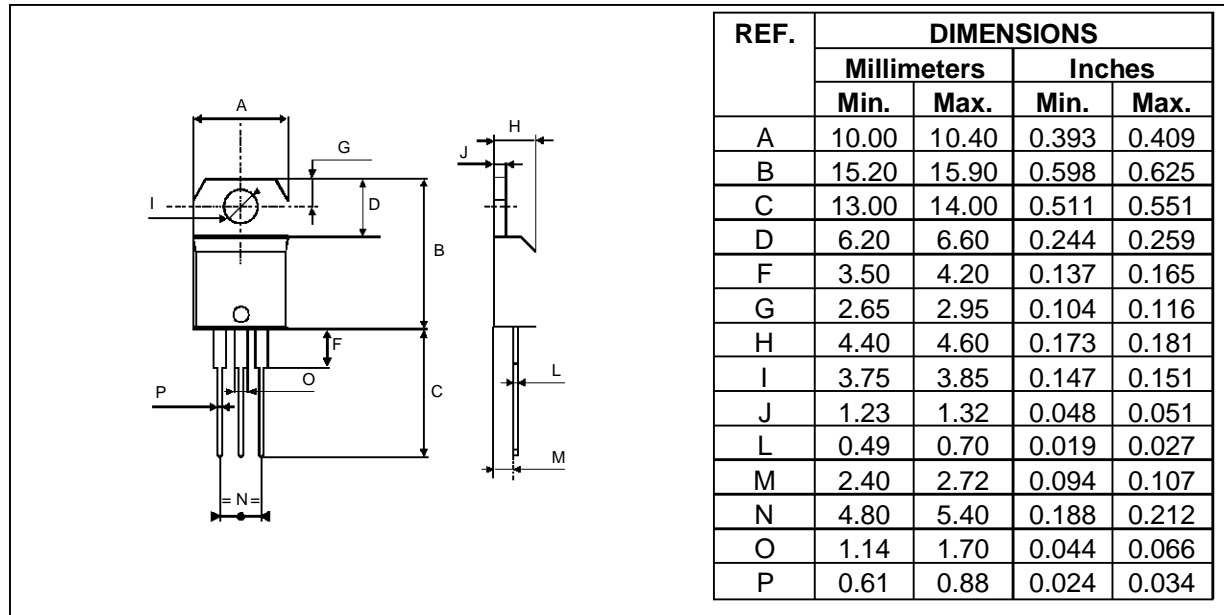


Fig.10 : Allowable peak capacitor discharge current versus initial junction temperature.



PACKAGE MECHANICAL DATA

TO220AB Plastic



Cooling method : C
 Marking : type number
 Weight : 2.3 g
 Recommended torque value : 0.8 m.N.
 Maximum torque value : 1 m.N.

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